IGBT for PFC Applications 650 V, 50 A, TO-247-3L

Features

- Maximum Junction Temperature: $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.6 \text{ V (Typ.)}$ @ $I_C = 50 \text{ A}$
- 100% of the Parts Tested for ILM (Note 1)
- High Input Impedance
- Fast Switching
- Tighten Parameter Distribution
- RoHS Compliant

Typical Applications

• Solar Inverter, UPS, Welder, Telecom, ESS, PFC

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Collector-to-Emitter Voltage		V _{CES}	650	V
Gate-to-Emitter Voltage	V_{GES}	±20	V	
Transient Gate-to-Emitter Voltage	V_{GES}	±30	٧	
Collector Current	T _C = 25°C	Ic	100	Α
	T _C = 100°C		50	
Pulsed Collector Current (Note 2)	T _C = 25°C	I _{CM}	200	Α
Maximum Power Dissipation	T _C = 25°C	P _D	268	W
	T _C = 100°C		134	
Operating Junction and Storage Te Range	T _J , T _{stg}	-55 to +175	°C	
Maximum Lead Temperature for So Purposes (1/8" from case for 5 s)	TL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

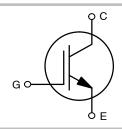
- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} = 200 A, Inductive Load 2. Repetitive rating: Pulse width limited by max. Junction temperature
- 3. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted



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BV _{CES}	V _{CE(sat)} TYP	I _C MAX
650 V	1.6 V	200 A





TO-247 LONG LEADS CASE 340CX

MARKING DIAGRAM



= ON Semiconductor Logo

&Z = Assembly Plant Code &3 = 3-Digit Date Code

\$Y

= 2-Digit Lot Traceability Code

FGHL50T65SQ = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FGHL50T65SQ	TO-247-3L	30 Units / Rail

Table 1. THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State	$R_{ heta JC}$	0.56	°C/W
Junction-to-Ambient - Steady State (Note 4)	$R_{\theta JA}$	40	

^{4.} Repetitive rating: Pulse width limited by max. Junction temperature

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS			-			
Collector to Emitter Breakdown Voltage	BV _{CES}	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	650			V
Temperature Coefficient of Breakdown Voltage	$\Delta V_{CES} / \Delta T_{J}$	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$		0.6		V/°C
Collector Cut-Off Current	I _{CES}	V _{CE} = V _{CES} , V _{GE} = 0 V			250	μΑ
G-E Leakage Current	I _{GES}	$V_{GE} = V_{GES}, V_{CE} = 0 V$			±400	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GE(th)}	$V_{GE} = V_{CE}$, $I_C = 50 \text{ mA}$	2.6	4.5	6.4	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	$I_C = 50 \text{ A}, V_{GE} = 15 \text{ V T}_C = 25^{\circ}\text{C}$		1.6	2.1	V
		I _C = 50 A, V _{GE} = 15 V T _C = 175°C		1.92		V
DYNAMIC CHARACTERISTIC						
Input Capacitance	Cies	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz		3209		pF
Output Capacitance	Coes			42		
Reverse Transfer Capacitance	Cres			12		
SWITCHING CHARACTERISTIC						
Turn-On Delay Time	t _{d(on)}	V_{CC} = 400 V, I_{C} = 25 A, R_{G} = 4.7 Ω , V_{GE} = 15 V, Inductive Load, T_{C} = 25°C		19		ns
Rise Time	t _r			13		ns
Turn-Off Delay Time	t _{d(off)}			93		ns
Fall Time	t _f			6.4		ns
Turn-On Switching Loss	E _{on}			410		μJ
Turn-Off Switching Loss	E _{off}			88		μJ
Total Switching Loss	E _{ts}			498		μJ
Turn-On Delay Time	t _{d(on)}	$V_{CC} = 400 \text{ V}, I_{C} = 25 \text{ A},$		18		ns
Rise Time	t _r	$R_G = 4.7 \Omega$, $V_{GE} = 15 V$, Inductive Load, $T_C = 175^{\circ}C$		15		ns
Turn-Off Delay Time	t _{d(off)}	FWD: FGH50T65SQD		102		ns
Fall Time	t _f			8		ns
Turn-On Switching Loss	E _{on}			641		μJ
Turn-Off Switching Loss	E _{off}			203		μJ
Total Switching Loss	E _{ts}			844		μJ
Total Gate Charge	Q_g	V _{CE} = 400 V, I _C = 50 A, V _{GE} = 15 V		99		nC
Gate-to-Emitter Charge	Q _{ge}	V _{GE} = 15 V		17		nC
Gate-to-Collector Charge	Q _{gc}			23		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

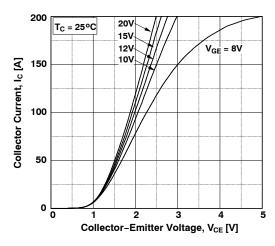


Figure 1. Typical Output Characteristics

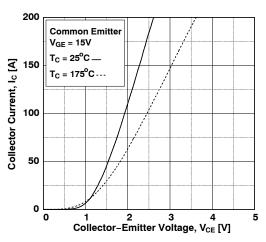


Figure 3. Typical Saturation Voltage Characteristics

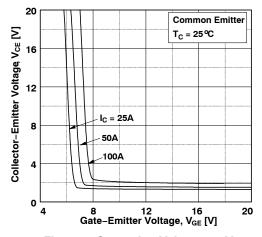


Figure 5. Saturation Voltage vs. V_{GE}

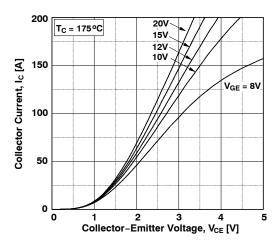


Figure 2. Typical Output Characteristics

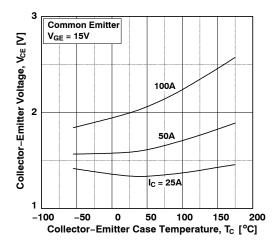


Figure 4. Saturation Voltage vs. Case Temperature at Variant Current Level

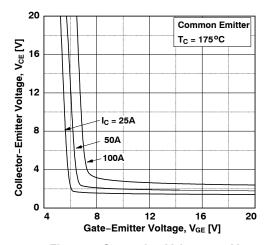


Figure 6. Saturation Voltage vs. V_{GE}

TYPICAL CHARACTERISTICS

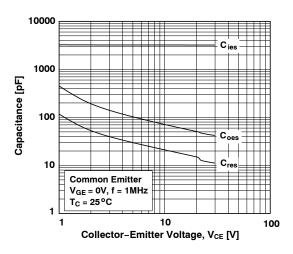


Figure 7. Capacitance Characteristics

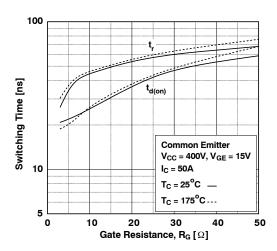


Figure 9. Turn-on Characteristics vs. Gate Resistance

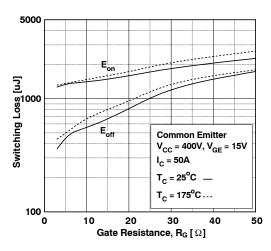


Figure 11. Switching Loss vs. Gate Resistance

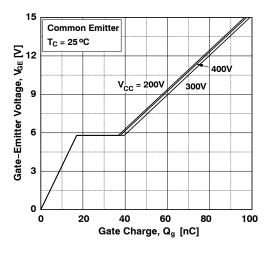


Figure 8. Gate Charge Characteristics

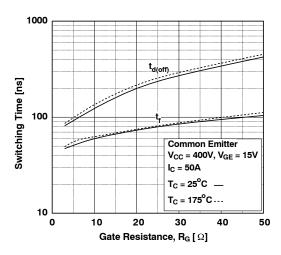


Figure 10. Turn-off Characteristics vs. Gate Resistance

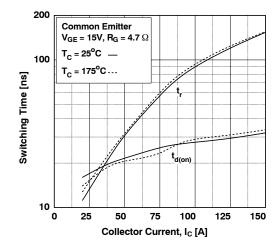


Figure 12. Turn-on Characteristics vs.
Collector Current

TYPICAL CHARACTERISTICS

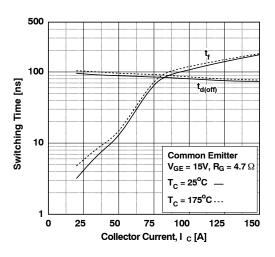


Figure 13. Turn-off Characteristics vs. Collector Current

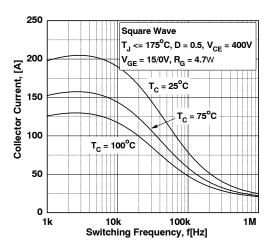


Figure 15. Load Current vs. Frequency

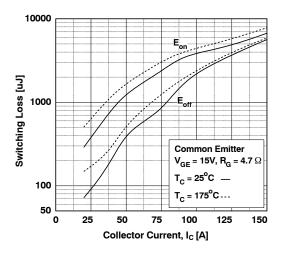


Figure 14. Switching Loss vs. Collector Current

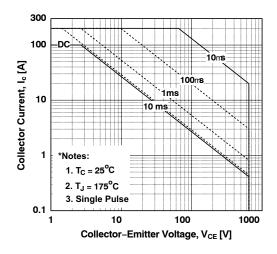


Figure 16. SOA Characteristics

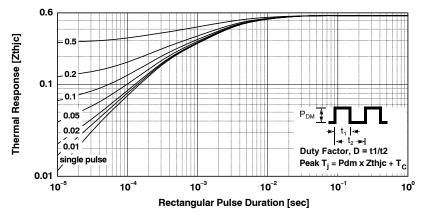
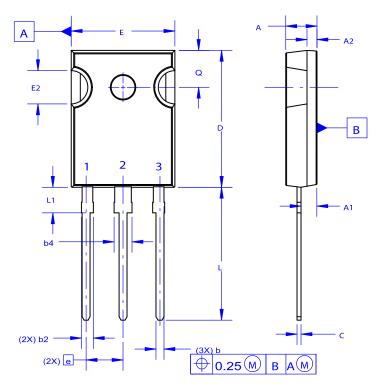


Figure 17. Transient Thermal Impedance of IGBT

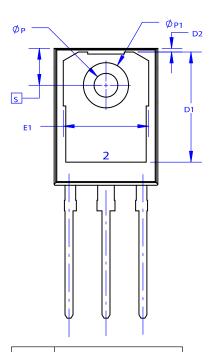
PACKAGE DIMENSIONS

TO-247-3LD CASE 340CX ISSUE O



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	?	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	?	~	
D2	0.51	0.93	1.35	
E1	12.81	?	~	
ØP1	6.60	6.80	7.00	

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